| PRODUCT NUMBER | NO. OF CONTACTS | DIM A | DIM B | DIM C | DIM D | DIM E | DIM F | DIM G | CONTACT PLATING NOTE 2 | HOLD-DOWN | PROCESSING CAP |
|---------------|----------------|-------|-------|-------|-------|-------|-------|-------|------------------------|-----------|----------------|---------|
| 91294-001     | 120            | 1.930/50.95 | 0.80/21.08 | 0.725/18.42 | 1.550/39.37 | 2.150/54.61 | 1.790/45.47 | 0.965/24.57 | 30 GXT | CABS INSTALLED ON CONNECTOR |
| 91294-002     | 160            | 2.430/61.72 | 1.080/27.43 | 0.975/24.76 | 2.050/52.07 | 2.650/67.31 | 2.290/58.16 | 1.215/30.86 | 30 GXT | CABS INSTALLED ON CONNECTOR |
| 91294-010     | 200            | 2.930/74.42 | 1.330/33.78 | 1.225/31.12 | 2.550/64.77 | 3.150/80.01 | 2.790/70.87 | 1.465/37.21 | 30 GXT | CABS INSTALLED ON CONNECTOR |
| 91294-011     | 160            | 1.930/50.95 | 0.80/21.08 | 0.725/18.42 | 1.550/39.37 | 2.150/54.61 | 1.790/45.47 | 0.965/24.57 | 30 GXT | CABS INSTALLED ON CONNECTOR |
| 91294-012     | 200            | 2.430/61.72 | 1.080/27.43 | 0.975/24.76 | 2.050/52.07 | 2.650/67.31 | 2.290/58.16 | 1.215/30.86 | 30 GXT | CABS INSTALLED ON CONNECTOR |
| 91294-013     | 200            | 2.930/74.42 | 1.330/33.78 | 1.225/31.12 | 2.550/64.77 | 3.150/80.01 | 2.790/70.87 | 1.465/37.21 | 30 GXT | CABS INSTALLED ON CONNECTOR |
| 91294-415     | 200            | 2.930/74.42 | 1.330/33.78 | 1.225/31.12 | 2.550/64.77 | 3.150/80.01 | 2.790/70.87 | 1.465/37.21 | 60 GXT | CAPS SUPPLIED LOOSE PIECE |

NOTES:

1. MATERIALS:
   - DIELECTRIC: LCP
   - CONTACTS: PHOS BRONZE
   - FRAME: ZINC ALLOY #3

2. PLATING:
   - SOLDER TAILS: 150 μ"/3.81um Sn Pb
   - FRAME: 150 μ"/3.81um BRIGHT TIN
   - CONTACTS: 30 μ"/0.76um GXT OVER 50 μ"/1.27um Ni OR 60 μ"/1.52um GXT OVER 75 μ"/1.90um Ni.

3. WHEN CONNECTOR IS WATED WITH OPPOSITE HALF, THE PARALLEL BD. TO BD. HCT IS 47 8.01. (APPLY TO VERT. THRU & SURFACE MT. STYLES)

4. THE SOLDER TAILS ON THIS PRODUCT ARE DESIGNED TO BE COMPLAINT IN ORDER TO ACCOMMODATE PRINTED CIRCUIT BOARD DIMENSIONAL VARIATIONS. THEREFORE, HOLD-DOWN HARDWARE IS REQUIRED TO SECURE THE CONNECTOR TO THE PRINTED CIRCUIT BOARD FOR MOST TYPES OF SOLDER REFLOW OPERATIONS. FOR FURTHER APPLICATION DATA, INCLUDING HOLE SIZES FOR VARIOUS TYPES OF HARDWARE, SEE TA-932.

5. DO NOT REMOVE PROCESSING CAP UNTIL SOLDERING IS COMPLETE.

6. BY ADDING LETTER "N" TO TABULATED P/N, THE OPTIONAL HOLD-DOWN WILL BE SUPPLIED INTEGRAL W/CONNECTOR. EXAMPLE: XXXXX-XXXH (HOLD-DOWN)

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**CUSTOMER COPY**

**MICROPAX .025M SMT PLUG DOUBLE MODULE**

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